# ABSTRACT

Disclosed are a substrate processing device, a substrate processing method, and a buffer module in relation to the technical field of semiconductor equipment. The substrate processing device comprises a drying module and a carrier member. The drying module includes a drying chamber; the carrier member is detachably arranged relative to the drying chamber. The carrier member includes a carrying portion and a blocking portion. The carrying portion is configured to carry a substrate. The blocking portion is disposed on the outer periphery of the carrying portion, and the blocking portion is configured such that when the carrying portion carries the substrate, the height of the blocking portion is not lower than the height of the substrate. Since the carrier member is detachably arranged relative to the drying chamber, the carrier member can be more easily taken out from the drying chamber. Compared to an integrated design of the carrier member and the drying chamber, the height and shape of the blocking portion can be adjusted more conveniently.

.